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Listing of Claims

1. (currently amended) A housing to receive a semiconductor wafer tray comprising:
at least four discrete positioning kits extending from interior sidewalls of the housing,
each positioning kit comprising:
a primary outside edge at least substantially corresponding to one of the interior
sidewalls of the housing; and,
an inside edge opposite of the primary outside edge, and having a groove at least
substantially corresponding to a part of a frame of the semiconductor wafer tray,
the groove receptive to the part of the frame of the semiconductor wafer tray, to
assist maintaining the semiconductor wafer tray in a stable position when the semiconductor
wafer tray is completely positioned in the housing, wherein the housing comprises a quartz tube
for a semiconductor fabrication rapid thermal process (RTP);
wherein at least one of the four positioning kits each extend from a back interior sidewall
of the interior sidewalls of the housing, at least one of the four positioning kits each extend from
a first side interior sidewall of the interior sidewalls of the housing, and at least one of the four
positioning kits each extend from a second side interior sidewall of the interior sidewalls of the
housing, the second side interior sidewall opposite to the first side interior sidewall.
2. (original) The housing of claim 1, wherein each positioning kit further comprises:
an upper outside edge facing an interior upper wall of the housing; and,
a lower outside edge facing an interior lower wall of the housing.
3. (original) The housing of claim 1, wherein the primary outside edge of each positioning
kit is fixed to the interior sidewall of the housing to which the primary outside edge at least
substantially corresponds.